

COATED COPPER WIRE FOR BONDING APPLICATIONS

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Abstract

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The invention is related to a bonding wire, comprising a core with a surface, wherein the core comprises copper as a main component, and a coating layer superimposed over the surface of the core, wherein the coating layer comprises palladium as a main component, wherein the core comprises silver and phosphorus as further components, wherein the core comprises copper as a main component, and

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a coating layer superimposed over the surface of the core, wherein the coating layer comprises palladium as a main component, wherein the core comprises silver and phosphorus as further components, wherein the ratio between the silver content and the phosphorus content of the core is in the range of 0.03 to 2.

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Fig. 1